

# TXB0104-Q1 Automotive 4-Bit Bidirectional Voltage-Level Translator with Automatic Direction Sensing and $\pm 15\text{kV}$ ESD Protection

## 1 Features

- Qualified for automotive applications
- AEC-Q100 qualified with the following results
  - Device temperature grade 1:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  ambient operating temperature range
- 1.2V to 3.6V on A port and 1.65V to 5.5V on B port ( $V_{CCA} \leq V_{CCB}$ )
- $V_{CC}$  isolation feature – if either  $V_{CC}$  input is at GND, all outputs are in the high-impedance state
- OE input circuit referenced to  $V_{CCA}$
- $I_{off}$  supports partial-power-down mode operation
- Latch-up performance exceeds 100mA per JESD 78, class II
- ESD protection exceeds JESD 22
  - A port
    - $\pm 2500\text{V}$  human-body model (A114-B)
    - $\pm 1000\text{V}$  charged-device model (C101)
  - B port
    - $\pm 15000\text{V}$  human-body model (A114-B)
    - $\pm 1000\text{V}$  charged-device model (C101)

## 2 Applications

- Automotive infotainment
- Advanced driver assistance system (ADAS)
- Telematics

## 3 Description

Voltage-level translators address the challenges posed by simultaneous use of different supply-voltage levels on the same circuit board. This 4-bit non-inverting translator uses two separate configurable

power-supply rails. The A port is designed to track  $V_{CCA}$ .  $V_{CCA}$  accepts any supply voltage from 1.2V to 3.6V. The B port is designed to track  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 1.65V to 5.5V. This allows for universal low-voltage bidirectional translation between any of the 1.2V, 1.5V, 1.8V, 2.5V, 3.3V, and 5V voltage nodes.  $V_{CCA}$  should not exceed  $V_{CCB}$ .

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state. To establish high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The TXB0104 is designed so that the OE input circuit is supplied by  $V_{CCA}$ .

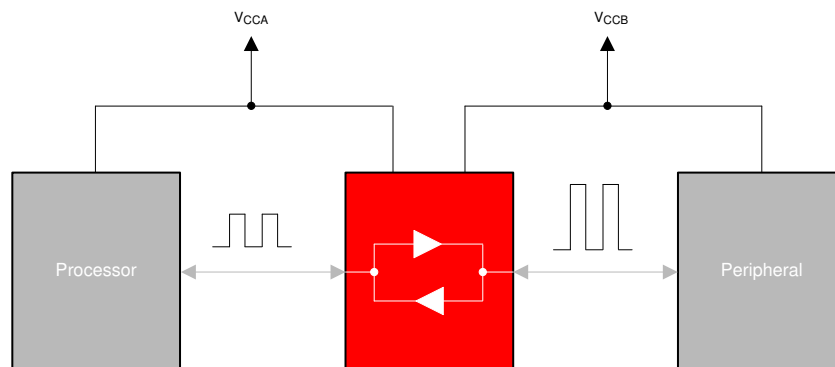
This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### Package Information

PART NUMBER <sup>(1)</sup>	PACKAGE	PACKAGE SIZE <sup>(2)</sup>
TXB0104-Q1	PW (TSSOP, 14)	5.00mm × 4.40mm
	RGY (VQFN, 14)	3.50mm × 3.50mm
	RUT (UQFN, 12)	2.00mm × 1.70mm
	BQA (WQFN, 14)	3.00mm × 2.5mm

(1) For more information, see [Section 11](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Typical Application Block Diagram for TXB010X

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## 4 Pin Configuration and Functions

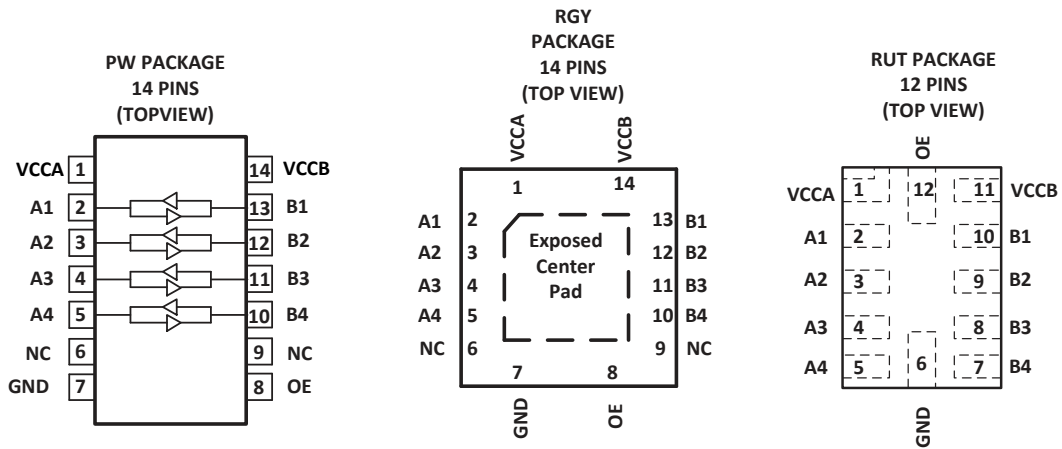


Figure 4-1. PW, RGY, and RUT Package (Top View)

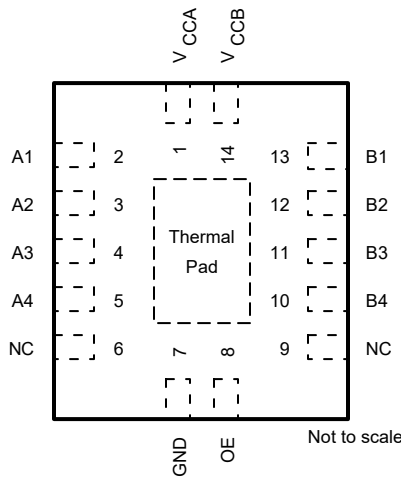


Figure 4-2. BQA Package, 14-Pin WQFN With Exposed Thermal Pad (Top View)

NC – No internal connection

For RGY, if the exposed center pad is used, it must be connected only to as a secondary ground or left electrically open.

**Table 4-1. Pin Functions**

PIN		I/O	DESCRIPTION
NO.	NAME		
1	VCCA	I	A-port supply voltage $1.2V \leq V_{CCA} \leq 3.6V$ and $V_{CCA} \leq V_{CCB}$ .
2	A1	I/O	Input/output 1. Referenced to $V_{CCA}$ .
3	A2	I/O	Input/output 2. Referenced to $V_{CCA}$ .
4	A3	I/O	Input/output 3. Referenced to $V_{CCA}$ .
5	A4	I/O	Input/output 4. Referenced to $V_{CCA}$ .
6	NC	–	No connection. Not internally connected.
7	GND	–	Ground
8	OE	I	3-state output-mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to $V_{CCA}$ .
9	NC	–	No connection. Not internally connected.
10	B4	I/O	Input/output 4. Referenced to $V_{CCB}$ .
11	B3	I/O	Input/output 3. Referenced to $V_{CCB}$ .
12	B2	I/O	Input/output 2. Referenced to $V_{CCB}$ .
13	B1	I/O	Input/output 1. Referenced to $V_{CCB}$ .
14	VCCB	I	B-port supply voltage $1.65V \leq V_{CCB} \leq 5.5V$ .

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

			MIN	MAX	UNIT
$V_{CCA}$	Supply voltage		-0.5	4.6	V
$V_{CCB}$			-0.5	6.5	
$V_I$	Input voltage	A port	-0.5	4.6	V
		B port	-0.5	6.5	
$V_O$	Voltage applied to any output in the high-impedance or power-off state	A port	-0.5	4.6	V
		B port	-0.5	6.5	
$V_O$	Voltage applied to any output in the high or low state <sup>(2)</sup>	A port	-0.5	$V_{CCA} + 0.5$	V
		B port	-0.5	$V_{CCB} + 0.5$	
$I_{IK}$	Input clamp current	$V_I < 0$		-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50	mA
$I_O$	Continuous output current			±50	mA
	Continuous current through $V_{CCA}$ , $V_{CCB}$ , or GND			±100	
$T_{stg}$	Storage temperature		-65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) The value of  $V_{CCA}$  and  $V_{CCB}$  are provided in the recommended operating conditions table.

### 5.2 ESD Ratings

			VALUE	UNIT	
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	A Port	±2500	V
			B Port	±15000	
		Charged-device model (CDM), per AEC Q100-011	A Port	±1000	
			B Port	±1000	

- (1) AEC Q100-002 indicates that HBM stressing must be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup> <sup>(2)</sup>

			$V_{CCA}$	$V_{CCB}$	MIN	MAX	UNIT
$V_{CCA}$	Supply voltage				1.2	3.6	V
					1.65	5.5	
$V_{IH}$	High-level input voltage	Data inputs	1.2V to 3.6V	1.65V to 5.5V	$V_{CCI} \times 0.65^{(3)}$	$V_{CCI}$	V
		OE	1.2V to 3.6V	1.65V to 5.5V	$V_{CCA} \times 0.65$	5.5	
$V_{IL}$	Low-level input voltage	Data inputs	1.2V to 5.5V	1.65V to 5.5V	0	$V_{CCI} \times 0.35^{(3)}$	V
		OE	1.2V to 3.6V	1.65V to 5.5V	0	$V_{CCA} \times 0.35$	
$V_O$	Voltage range applied to any output in the high-impedance or power-off state	A-port	1.2V to 3.6V	1.65V to 5.5V	0	3.6	V
		B-port			0	5.5	
$\Delta t/\Delta v$	Input transition Rise or fall rate	A-port inputs	1.2V to 3.6V	1.65V to 5.5V		40	ns/V
		B-port inputs	1.2V to 3.6V	1.65V to 3.6V		40	
				4.5V to 5.5V		30	

### 5.3 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	MAX	UNIT
T <sub>A</sub> Operating free-air temperature			-40	125	°C

- (1) The A and B sides of an unused data I/O pair must be held in the same state, that is, both at V<sub>CCI</sub> or both at GND.
- (2) V<sub>CCA</sub> must be less than or equal to V<sub>CCB</sub> and must not exceed 3.6V.
- (3) V<sub>CCI</sub> is the supply voltage associated with the input port.

### 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TXB0104-Q1				UNIT
		PW	RGY	RUT	BQA	
		14 PINS	14 PINS	12 PINS	14 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	121	52.8	119.8	77.1	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	50	67.7	42.6	80.7	
R <sub>θJB</sub>	Junction-to-board thermal resistance	62.8	28.9	52.5	46.9	
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	6.4	2.6	0.7	6.1	
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	62.2	29.0	52.3	46.8	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	9.3	N/A	23.3	

- (1) For more information about traditional and new thermal metrics, see the [IC Package Thermal Metrics](#) application note.

### 5.5 Electrical Characteristics (BQA)

over recommended operating free-air temperature range (unless otherwise noted) <sup>(1) (2)</sup>

PARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			-40°C to 125°C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>OHA</sub>	I <sub>OH</sub> = -20μA	1.2V			1.1		V <sub>CCA</sub> - 0.4			V
		1.4V to 3.6V								
V <sub>OLA</sub>	I <sub>OL</sub> = 20μA	1.2V			0.9				V	
		1.4V to 3.6V					0.4			
V <sub>OHB</sub>	I <sub>OH</sub> = -20μA		1.65V to 5.5V				V <sub>CCB</sub> - 0.4		V	
V <sub>OLB</sub>	I <sub>OL</sub> = 20μA		1.65V to 5.5V					0.4	V	
I <sub>I</sub>	OE	V <sub>I</sub> = V <sub>CCI</sub> or GND	1.2V to 3.6V	1.65V to 5.5V		±1			±5	μA
I <sub>off</sub>	A port	V <sub>I</sub> or V <sub>O</sub> = 0 to 3.6V	0V	0V to 5.5V		±1			±10	μA
	B port	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5V	0V to 3.6V	0V		±1			±10	
I <sub>OZ</sub>	A or B port	OE = GND	1.2V to 3.6V	1.65V to 5.5V		±1			±10	μA
I <sub>CCA</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V		0.4				μA	
		1.4V to 3.6V	1.65V to 5.5V					20		
		3.6V	0V					15		
		0V	5.5V					-15		
I <sub>CCB</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V		3.4				μA	
		1.4V to 3.6V	1.65V to 5.5V					20		
		3.6V	0V					-15		
		0V	5.5V					15		
I <sub>CCA</sub> + I <sub>CCB</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V		3.5				μA	
		1.4V to 3.6V	1.65V to 5.5V					40		

over recommended operating free-air temperature range (unless otherwise noted) <sup>(1)</sup> <sup>(2)</sup>

PARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			–40°C to 125°C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
I <sub>CCZA</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V		0.4					μA
		1.4V to 3.6V	1.65V to 5.5V					15		
I <sub>CCZB</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V		3.3					μA
		1.4V to 3.6V	1.65V to 5.5V					15		
C <sub>i</sub>	OE	BQA package	1.2V to 3.6V	1.65V to 5.5V		4				pF
C <sub>io</sub>	A port	BQA package	1.2V to 3.6V	1.65V to 5.5V		6				pF
	B port	BQA package				13				pF

- (1) V<sub>CC1</sub> is the supply voltage associated with the input port.  
(2) V<sub>CC0</sub> is the supply voltage associated with the output port.

## 5.6 Electrical Characteristics (Other Packages)

over recommended operating free-air temperature range (unless otherwise noted) <sup>(1)</sup> <sup>(2)</sup>

PARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			–40°C to 125°C			UNIT	
				MIN	TYP	MAX	MIN	TYP	MAX		
V <sub>OHA</sub>	I <sub>OH</sub> = –20μA	1.2V		1.1			V <sub>CCA</sub> – 0.4			V	
		1.4V to 3.6V									
V <sub>OLA</sub>	I <sub>OL</sub> = 20μA	1.2V		0.9			0.4			V	
		1.4V to 3.6V									
V <sub>OHB</sub>	I <sub>OH</sub> = –20μA		1.65V to 5.5V				V <sub>CCB</sub> – 0.4			V	
V <sub>OLB</sub>	I <sub>OL</sub> = 20μA		1.65V to 5.5V				0.4			V	
I <sub>I</sub>	OE	V <sub>I</sub> = V <sub>CC1</sub> or GND	1.2V to 3.6V	1.65V to 5.5V	±1			±5			μA
I <sub>off</sub>	A port	V <sub>I</sub> or V <sub>O</sub> = 0 to 3.6V	0V	0V to 5.5V	±1			±10			μA
	B port	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5V	0V to 3.6V	0V	±1			±10			
I <sub>OZ</sub>	A or B port	OE = GND	1.2V to 3.6V	1.65V to 5.5V	±1			±10			μA
I <sub>CCA</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	0.06						μA	
		1.4V to 3.6V	1.65V to 5.5V				20				
		3.6V	0V				15				
		0V	5.5V				–15				
I <sub>CCB</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	3.4						μA	
		1.4V to 3.6V	1.65V to 5.5V				20				
		3.6V	0V				–15				
		0V	5.5V				15				
I <sub>CCA</sub> + I <sub>CCB</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	3.5						μA	
		1.4V to 3.6V	1.65V to 5.5V				40				
I <sub>CCZA</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V	0.05						μA	
		1.4V to 3.6V	1.65V to 5.5V				15				
I <sub>CCZB</sub>	V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V	3.3						μA	
		1.4V to 3.6V	1.65V to 5.5V				15				
C <sub>i</sub>	OE	PW, RGY, BQA package	1.2V to 3.6V	1.65V to 5.5V	3						pF
		RUT package	1.2V to 3.6V	1.65V to 5.5V	4						pF

## 5.6 Electrical Characteristics (Other Packages) (continued)

over recommended operating free-air temperature range (unless otherwise noted) <sup>(1)</sup> <sup>(2)</sup>

PARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			–40°C to 125°C			UNIT	
				MIN	TYP	MAX	MIN	TYP	MAX		
C <sub>io</sub>	A port	PW, RGY, BQA package	1.2V to 3.6V	1.65V to 5.5V	5						pF
		RUT package			6						pF
	B port	PW, RGY, BQA package			11						pF
		RUT package			13						pF

(1) An external driver must source at least I<sub>BHLO</sub> to switch this node from low to high.

(2) An external driver must sink at least I<sub>BHHO</sub> to switch this node from high to low.

## 5.7 Timing Requirements: V<sub>CCA</sub> = 1.2V

T<sub>A</sub> = 25°C, V<sub>CCA</sub> = 1.2V

		V <sub>CCB</sub> = 1.8V	V <sub>CCB</sub> = 2.5V	V <sub>CCB</sub> = 3.3V	V <sub>CCB</sub> = 5V	UNIT
		TYP	TYP	TYP	TYP	
Data rate	For PW, RGY, BQA, RUT package	20	20	20	20	Mbps
t <sub>w</sub>	Pulse duration	50	50	50	50	ns

## 5.8 Timing Requirements: V<sub>CCA</sub> = 1.5V ± 0.1V

over recommended operating free-air temperature range, V<sub>CCA</sub> = 1.5V ± 0.1V (unless otherwise noted)

		V <sub>CCB</sub> = 1.8V ± 0.15V		V <sub>CCB</sub> = 2.5V ± 0.2V		V <sub>CCB</sub> = 3.3V ± 0.3V		V <sub>CCB</sub> = 5V ± 0.5V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Data rate	For PW, RGY, BQA package	40		40		40		40		Mbps
	For RUT package	37		37		40		40		Mbps
t <sub>w</sub>	Data inputs, For PW, RGY, BQA package	25		25		25		25		ns
	Data inputs, For RUT package	27		27		25		25		ns

## 5.9 Timing Requirements: V<sub>CCA</sub> = 1.8V ± 0.15V

over recommended operating free-air temperature range, V<sub>CCA</sub> = 1.8V ± 0.15V (unless otherwise noted)

		V <sub>CCB</sub> = 1.8V ± 0.15V		V <sub>CCB</sub> = 2.5V ± 0.2V		V <sub>CCB</sub> = 3.3V ± 0.3V		V <sub>CCB</sub> = 5V ± 0.5V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Data rate	For PW, RGY, BQA package	55		55		55		55		Mbps
	For RUT package	37		37		55		55		Mbps
t <sub>w</sub>	Data inputs, For PW, RGY, BQA package	18		18		18		18		ns
	Data inputs, For RUT package	27		27		18		18		ns



### 5.10 Timing Requirements: $V_{CCA} = 2.5V \pm 0.2V$

over recommended operating free-air temperature range,  $V_{CCA} = 2.5V \pm 0.2V$  (unless otherwise noted)

		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Data rate	For PW, RGY, BQA package	75		80		100		Mbps
	For RUT package	65		80		85		Mbps
$t_w$	Pulse duration	13		12		10		ns
	Data inputs, For RUT package	15		12		11		ns

### 5.11 Timing Requirements: $V_{CCA} = 3.3V \pm 0.3V$

over recommended operating free-air temperature range,  $V_{CCA} = 3.3V \pm 0.3V$  (unless otherwise noted)

		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
		MIN	MAX	MIN	MAX	
Data rate	For PW, RGY, BQA package	100		100		Mbps
	For RUT package	90		90		Mbps
$t_w$	Pulse duration	10		10		ns
	Data inputs, For RUT package	11		11		ns

### 5.12 Switching Characteristics: $V_{CCA} = 1.2V$ (BQA)

$T_A = 25^\circ C$ ,  $V_{CCA} = 1.2V$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V$	$V_{CCB} = 2.5V$	$V_{CCB} = 3.3V$	$V_{CCB} = 5V$	UNIT
			TYP	TYP	TYP	TYP	
$t_{pd}$	A	B	6.9	5.7	5.3	5.5	ns
	B	A	7.4	6.4	6	5.8	
$t_{en}$	OE	A	1	1	1	1	$\mu s$
		B	1	1	1	1	
$t_{dis}$	OE	A	392	392	392	392	ns
		B	392	392	392	392	
$t_{rA}, t_{fA}$	A-port rise and fall times		4.2	4.2	4.2	4.2	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		2.1	1.5	1.2	1.1	ns

### 5.13 Switching Characteristics: $V_{CCA} = 1.2V$ (Other Packages)

$T_A = 25^\circ C$ ,  $V_{CCA} = 1.2V$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V$	$V_{CCB} = 2.5V$	$V_{CCB} = 3.3V$	$V_{CCB} = 5V$	UNIT
			TYP	TYP	TYP	TYP	
$t_{pd}$	A	B	6.9	5.7	5.3	5.5	ns
	B	A	7.4	6.4	6	5.8	
$t_{en}$	OE	A	1	1	1	1	$\mu s$
		B	1	1	1	1	
$t_{dis}$	OE	A	320	320	320	330	ns
		B	150	110	150	110	
$t_{rA}, t_{fA}$	A-port rise and fall times		4.2	4.2	4.2	4.2	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		2.1	1.5	1.2	1.1	ns

### 5.14 Switching Characteristics: $V_{CCA} = 1.5V \pm 0.1V$ (BQA)

over recommended operating free-air temperature range,  $V_{CCA} = 1.5V \pm 0.1V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B		15.9		13.1		13		12.9	ns
	B	A		17.2		15		14.7		16.7	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A		390		305		305		305	ns
		B		390		305		305		305	
$t_{rA}, t_{fA}$	A-port rise and fall times			7.1		7.1		7.1		7.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times			6.5		5.2		4.8		4.7	ns

### 5.15 Switching Characteristics: $V_{CCA} = 1.5V \pm 0.1V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 1.5V \pm 0.1V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B		15.9		13.1		13		12.9	ns
	B	A		17.2		15		14.7		16.7	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A		340		280		280		300	ns
		B		220		220		220		220	
$t_{rA}, t_{fA}$	A-port rise and fall times			7.1		7.1		7.1		7.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times			6.5		5.2		4.8		4.7	ns

### 5.16 Switching Characteristics: $V_{CCA} = 1.8V \pm 0.15V$ (BQA)

over recommended operating free-air temperature range,  $V_{CCA} = 1.8V \pm 0.15V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B		14		10.7		9.8		9.5	ns
	B	A		15		11.4		10.6		10.1	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A		389		253		250		250	ns
		B		389		253		248		248	
$t_{rA}, t_{fA}$	A-port rise and fall times			6.2		6.1		6.1		6.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times			5.8		5.2		4.8		4.7	ns

### 5.17 Switching Characteristics: $V_{CCA} = 1.8V \pm 0.15V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 1.8V \pm 0.15V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	14		10.7		9.8		9.5		ns
	B	A	15		11.4		10.6		10.1		
$t_{en}$	OE	A	1		1		1		1		$\mu s$
		B	1		1		1		1		
$t_{dis}$	OE	A	280		250		250		250		ns
		B	220		220		220		220		
$t_{rA}, t_{fA}$	A-port rise and fall times		6.2		6.1		6.1		6.1		ns
$t_{rB}, t_{fB}$	B-port rise and fall times		5.8		5.2		4.8		4.7		ns

### 5.18 Switching Characteristics: $V_{CCA} = 2.5V \pm 0.2V$ (BQA)

over recommended operating free-air temperature range,  $V_{CCA} = 2.5V \pm 0.2V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	9.3		8.2		7.7		ns
	B	A	9.6		8.1		7.4		
$t_{en}$	OE	A	1		1		1		$\mu s$
		B	1		1		1		
$t_{dis}$	OE	A	252		220		220		ns
		B	252		220		220		
$t_{rA}, t_{fA}$	A-port rise and fall times		5		5		5		ns
$t_{rB}, t_{fB}$	B-port rise and fall times		4.6		4.8		4.7		ns

### 5.19 Switching Characteristics: $V_{CCA} = 2.5V \pm 0.2V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 2.5V \pm 0.2V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	9.3		8.2		7.7		ns
	B	A	9.6		8.1		7.4		
$t_{en}$	OE	A	1		1		1		$\mu s$
		B	1		1		1		
$t_{dis}$	OE	A	220		220		220		ns
		B	220		220		220		
$t_{rA}, t_{fA}$	A-port rise and fall times		5		5		5		ns
$t_{rB}, t_{fB}$	B-port rise and fall times		4.6		4.8		4.7		ns

### 5.20 Switching Characteristics: $V_{CCA} = 3.3V \pm 0.3V$

over recommended operating free-air temperature range,  $V_{CCA} = 3.3V \pm 0.3V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	7.7		7		ns
	B	A	7.9		6.8		
$t_{en}$	OE	A	1		1		$\mu s$
		B	1		1		
$t_{dis}$	OE	A	280		280		ns
		B	220		220		
$t_{rA}, t_{fA}$	A-port rise and fall times		4.5		4.5		ns
$t_{rB}, t_{fB}$	B-port rise and fall times		4.1		4.7		ns

### 5.21 Operating Characteristics

$T_A = 25^\circ C$  (1)

PARAMETER	TEST CONDITIONS	$V_{CCA}$							UNIT	
		1.2V	1.2V	1.5V	1.8V	2.5V	2.5V	3.3V		
		$V_{CCB}$								
		5V	1.8V	1.8V	1.8V	2.5V	5V	3.3V to 5V		
		TYP	TYP	TYP	TYP	TYP	TYP	TYP		
$C_{pdA}$	A-port input, B-port output	$C_L = 0, f = 10MHz,$ $t_r = t_f = 1ns,$ OE = $V_{CCA}$ (outputs enabled)	7.8	10	9	8	8	8	9	pF
	B-port input, A-port output		12	11	11	11	11	11	11	
$C_{pdB}$	A-port input, B-port output		38.1	28	28	28	29	29	29	
	B-port input, A-port output		25.4	19	18	18	19	21	22	
$C_{pdA}$	A-port input, B-port output	$C_L = 0, f = 10MHz,$ $t_r = t_f = 1ns,$ OE = GND (outputs disabled)	0.01	0.01	0.01	0.01	0.01	0.01	0.01	pF
	B-port input, A-port output		0.01	0.01	0.01	0.01	0.01	0.01	0.01	
$C_{pdB}$	A-port input, B-port output		0.01	0.01	0.01	0.01	0.01	0.01	0.03	
	B-port input, A-port output		0.01	0.01	0.01	0.01	0.01	0.01	0.04	

- (1)  $C_{pd}$  parameter is the capacitance used to determine the no-load dynamic power dissipation per logic function for CMOS devices as per the formula:  $P_D = C_{pd} (V_{CC})^2 + I_{CC} V_{CC}$ . For more details about the use of  $C_{pd}$  to calculate power dissipation, refer to the [CMOS Power Consumption and  \$C\_{pd}\$  Calculation](#) application note.

## 5.22 Typical Characteristics

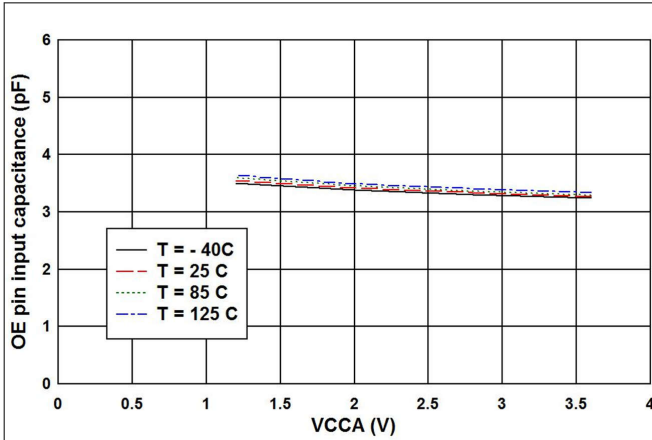


Figure 5-1. Input capacitance for OE pin ( $C_i$ ) vs Power Supply ( $V_{CCA}$ ) for  $V_{CCB} = 3.3V$  (RUT package)

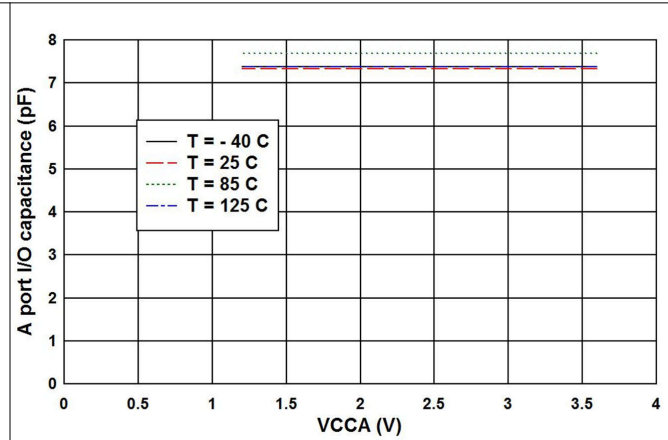


Figure 5-2. Capacitance for A port I/O pins ( $C_{iO}$ ) vs Power Supply ( $V_{CCA}$ ) for  $V_{CCB} = 3.3V$  (RUT package)

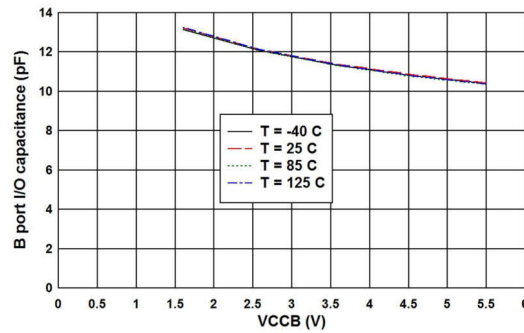
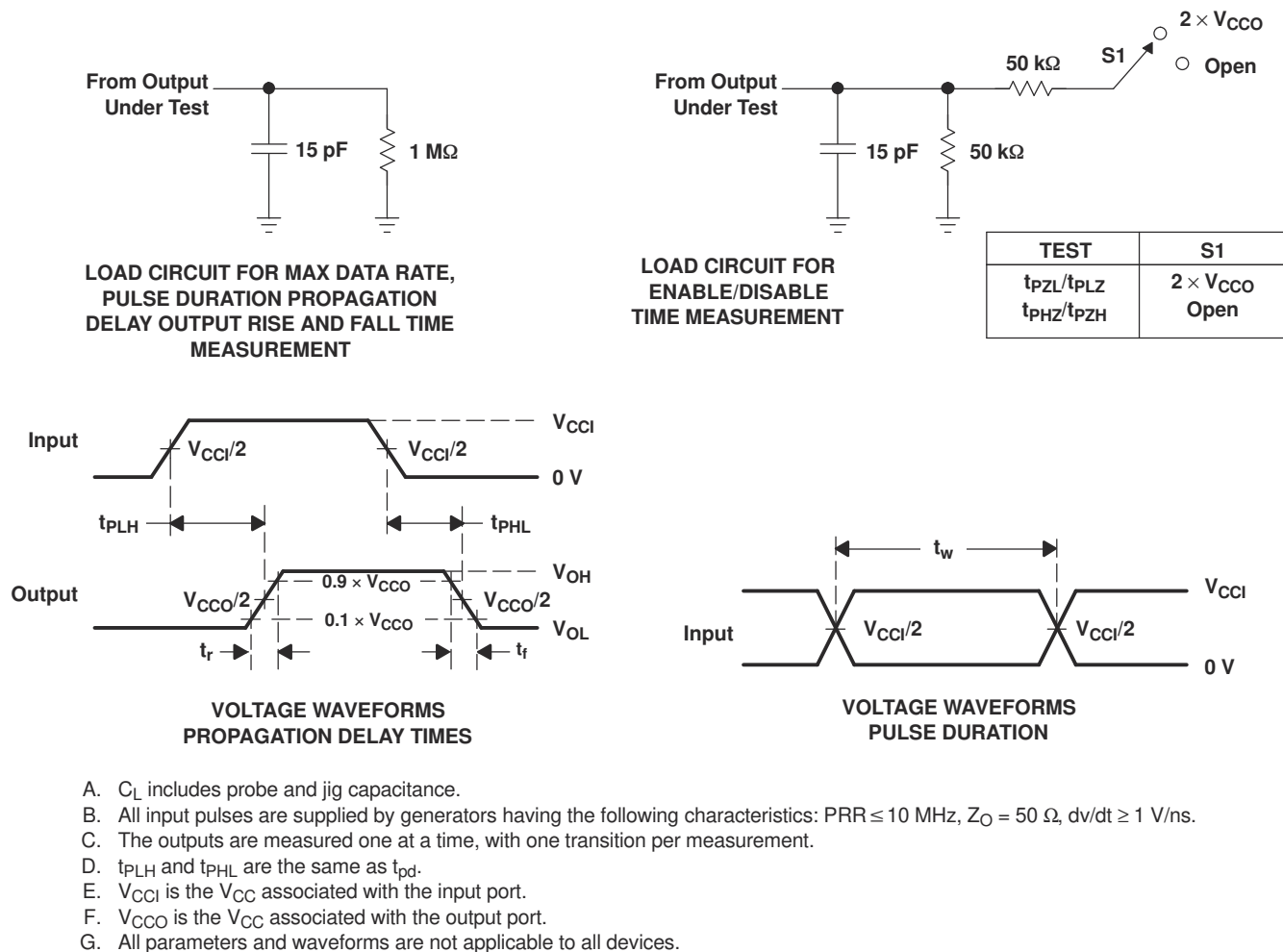


Figure 5-3. Capacitance for B port I/O pins ( $C_{iO}$ ) vs Power Supply ( $V_{CCB}$ ) for  $V_{CCA} = 3.3V$  (RUT package)

## 6 Parameter Measurement Information



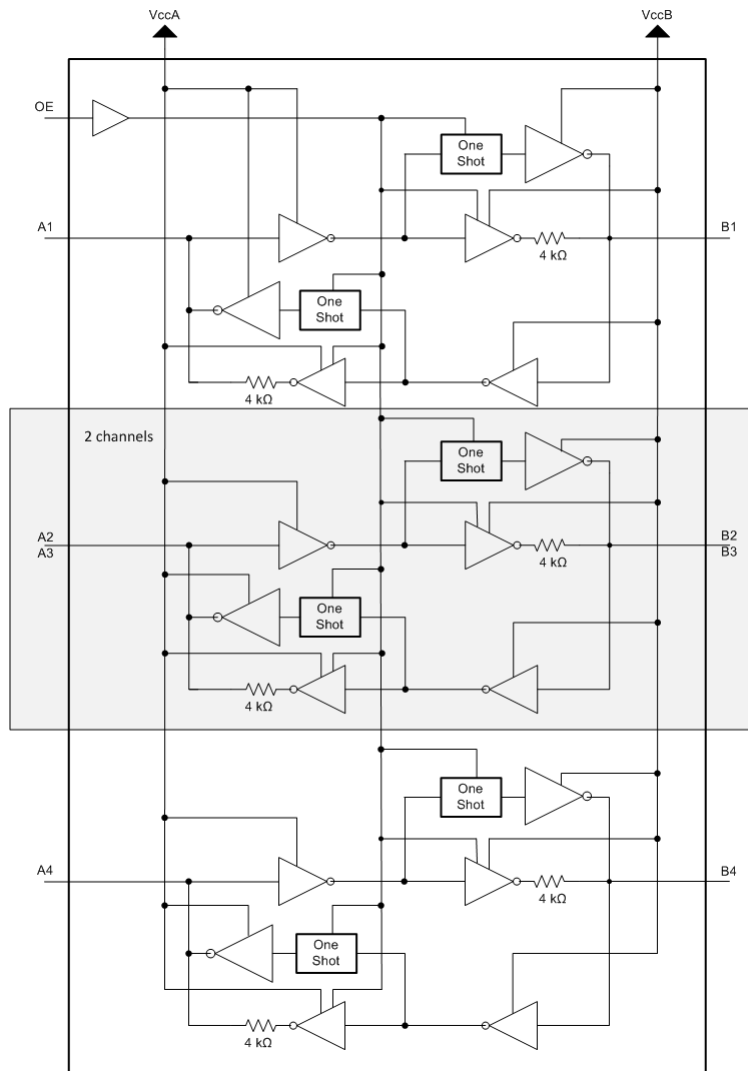
**Figure 6-1. Load Circuits and Voltage Waveforms**

## 7 Detailed Description

### 7.1 Overview

The TXB0104 device is a 4-bit, bi-directional voltage-level translator specifically designed for translating logic voltage levels. The A port is able to accept I/O voltages ranging from 1.2V to 3.6V, while the B port can accept I/O voltages from 1.65V to 5.5V. The device is a buffered architecture with edge-rate accelerators (one-shots) to improve the overall data rate. This device can only translate push-pull CMOS logic outputs. If for open-drain signal translation, please refer to TI's TXS010X products.

### 7.2 Functional Block Diagram



## 7.3 Feature Description

### 7.3.1 Architecture

The TXB0104 architecture (see [Section 7.2](#)) does not require a direction-control signal to control the direction of data flow from A to B or from B to A. In a DC state, the output drivers of the TXB0104 can maintain a high or low, but are designed to be weak, so that they can be overdriven by an external driver when data on the bus starts flowing the opposite direction.

The output one-shots detect rising or falling edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1, T3) for a short duration, which speeds up the low-to-high transition. Similarly, during a falling edge, the one-shot turns on the NMOS transistors (T2, T4) for a short duration which speeds up the high-to-low transition. The typical output impedance during output transition is 70Ω at  $V_{CCO} = 1.2V$  to 1.8V, 50Ω at  $V_{CCO} = 1.8V$  to 3.3V, and 40Ω at  $V_{CCO} = 3.3V$  to 5V.

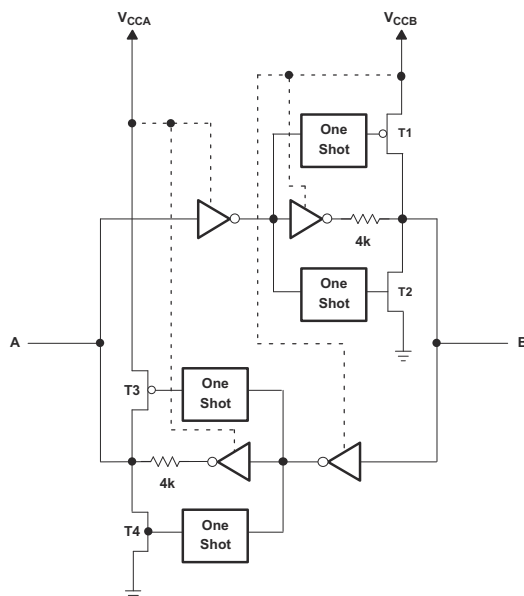


Figure 7-1. Architecture of TXB0104 I/O Cell

### 7.3.2 Input Driver Requirements

Typical  $I_{IN}$  vs  $V_{IN}$  characteristics of the TXB0104 are shown in [Figure 7-2](#). For proper operation, the device driving the data I/Os of the TXB0104 must have drive strength of at least  $\pm 2mA$ .

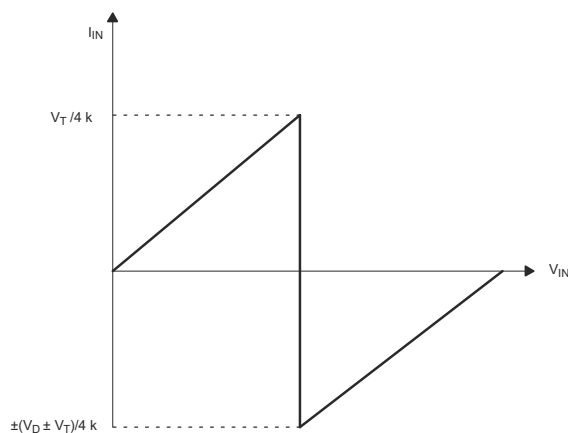


Figure 7-2. Typical  $I_{IN}$  vs  $V_{IN}$  Curve



### 7.3.3 Output Load Considerations

TI recommends careful PCB layout practices with short PCB trace lengths to avoid excessive capacitive loading and to verify that proper one shot (O.S.) triggering takes place. PCB signal trace-lengths should be kept short enough such that the round trip delay of any reflection is less than the one-shot duration. This improves signal integrity by ensuring that any reflection sees a low impedance at the driver. The O.S. circuits have been designed to stay on for approximately 10ns. The maximum capacitance of the lumped load that can be driven also depends directly on the one-shot duration. With very heavy capacitive loads, the one-shot can time-out before the signal is driven fully to the positive rail. The O.S. duration has been set to best optimize trade-offs between dynamic  $I_{CC}$ , load driving capability, and maximum bit-rate considerations. Both PCB trace length and connectors add to the capacitance that the TXB0104 output sees, so it is recommended that this lumped-load capacitance be considered to avoid O.S. retriggering, bus contention, output signal oscillations, or other adverse system-level affects.

### 7.3.4 Enable and Disable

The TXB0104 has an OE input that is used to disable the device by setting OE = low, which places all I/Os in the high-impedance (Hi-Z) state. The disable time ( $t_{dis}$ ) indicates the delay between when OE goes low and when the outputs actually get disabled (Hi-Z). The enable time ( $t_{en}$ ) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

### 7.3.5 Pullup or Pulldown Resistors on I/O Lines

The TXB0104 is designed to drive capacitive loads of up to 70pF. The output drivers of the TXB0104 have low DC drive strength. If pullup or pulldown resistors are connected externally to the data I/Os, their values must be kept higher than 50k $\Omega$  to ensure that they do not contend with the output drivers of the TXB0104.

For the same reason, the TXB0104 should not be used in applications such as I<sup>2</sup>C or 1-Wire where an open-drain driver is connected on the bidirectional data I/O. For these applications, use a device from the TI TXS01xx series of level translators.

## 7.4 Device Functional Modes

The TXB0104 device has two functional modes, enabled and disabled. To disable the device, set the OE input to low, which places all I/Os in a high impedance state. Setting the OE input to high enables the device.

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TXB0104 can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. It can only translate push-pull CMOS logic outputs. If for open-drain signal translation, please refer to TI TXS010X products. Any external pulldown or pullup resistors are recommended larger than 50k $\Omega$ .

### 8.2 Typical Application

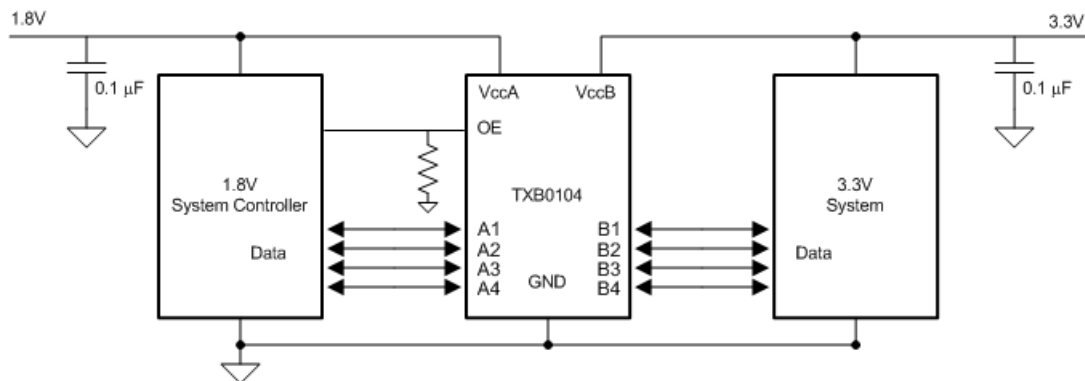


Figure 8-1. Typical Application Schematic

#### 8.2.1 Design Requirements

For this design example, use the parameters listed in [Table 8-1](#). And make sure the  $V_{CCA} \leq V_{CCB}$ .

Table 8-1. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUE
Input voltage range	1.2V to 3.6V
Output voltage range	1.65V to 5.5V

#### 8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

##### Input Voltage Range

Use the supply voltage of the device that is driving the TXB0104 device to determine the input voltage range. For a valid logic high the value must exceed the  $V_{IH}$  of the input port. For a valid logic low the value must be less than the  $V_{IL}$  of the input port.

##### Output Voltage Range

Use the supply voltage of the device that the TXB0104 device is driving to determine the output voltage range. It is not recommended to have the external pullup or pulldown resistors. If mandatory, it is recommended the value should be larger than 50k $\Omega$ .

An external pulldown or pullup resistor decreases the output  $V_{OH}$  and  $V_{OL}$ . Use the below equations to draft estimate the  $V_{OH}$  and  $V_{OL}$  as a result of an external pulldown and pullup resistor.

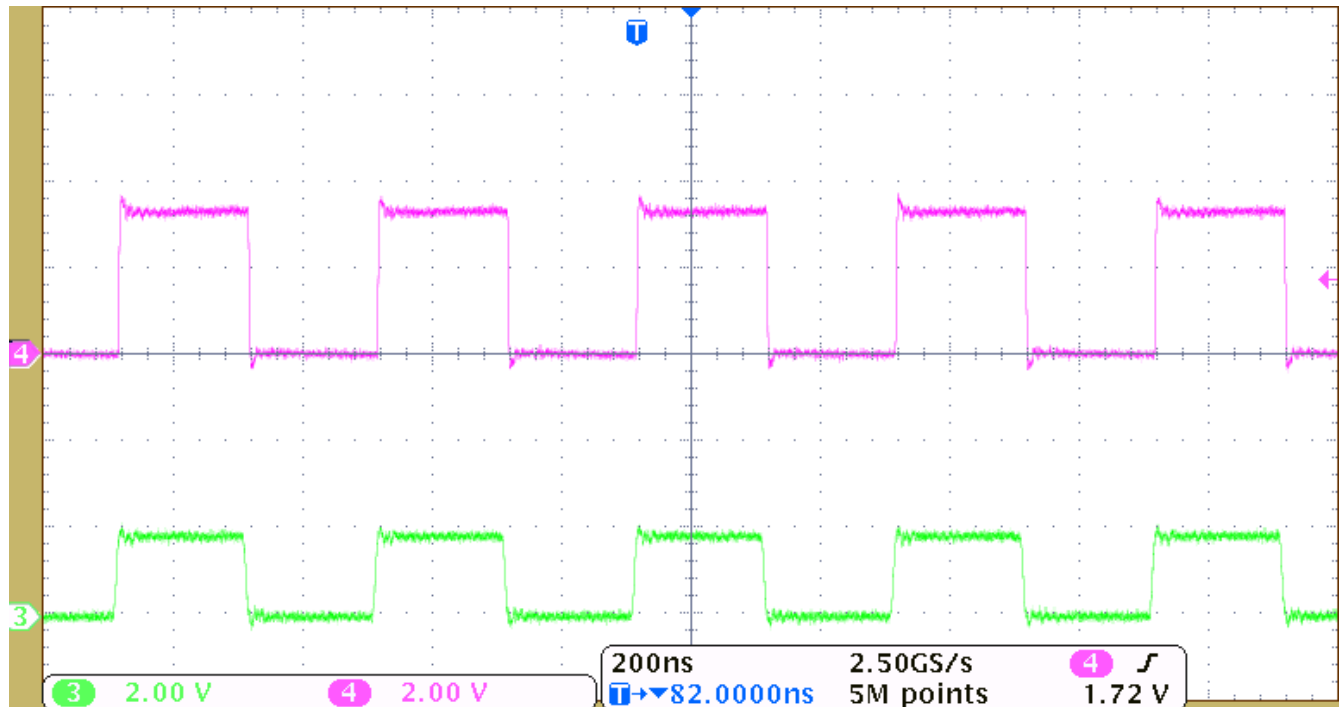
$$V_{OH} = V_{CCx} \times R_{PD} \div (R_{PD} + 4.5k\Omega) \quad (1)$$

$$V_{OL} = V_{CCx} \times 4.5k\Omega \div (R_{PU} + 4.5k\Omega) \quad (2)$$

where

- $V_{CCx}$  is the output port supply voltage on either  $V_{CCA}$  or  $V_{CCB}$
- $R_{PD}$  is the value of the external pull down resistor
- $R_{PU}$  is the value of the external pull up resistor
- 4.5k $\Omega$  is the counting the variation of the serial resistor 4k $\Omega$  in the I/O line

### 8.2.3 Application Curve



**Figure 8-2. Example of Level Translation of a 2.5MHz 1.8V Signal (Green) to a 3.3V Signal (Pink)**

## 8.3 Power Supply Recommendations

During operation, ensure that  $V_{CCA} \leq V_{CCB}$  at all times. During power-up sequencing,  $V_{CCA} \geq V_{CCB}$  does not damage the device, so any power supply can be ramped up first. The TXB0104 has circuitry that disables all output ports when either  $V_{CC}$  is switched off ( $V_{CCA/B} = 0V$ ). The output-enable (OE) input circuit is designed so that it is supplied by  $V_{CCA}$  and when the (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pulldown resistor and must not be enabled until  $V_{CCA}$  and  $V_{CCB}$  are fully ramped and stable. The minimum value of the pulldown resistor to ground is determined by the current-sourcing capability of the driver.

## 8.4 Layout

### 8.4.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines are recommended:

- Use bypass capacitors on power supplies. Place the bypass capacitors as close as possible to the  $V_{CCA}$ ,  $V_{CCB}$  pin, and GND pin
- Use short trace-lengths to avoid excessive loading.

- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one-shot duration, approximately 10ns, to verify that any reflection encounters low impedance at the source driver.

### 8.4.2 Layout Example

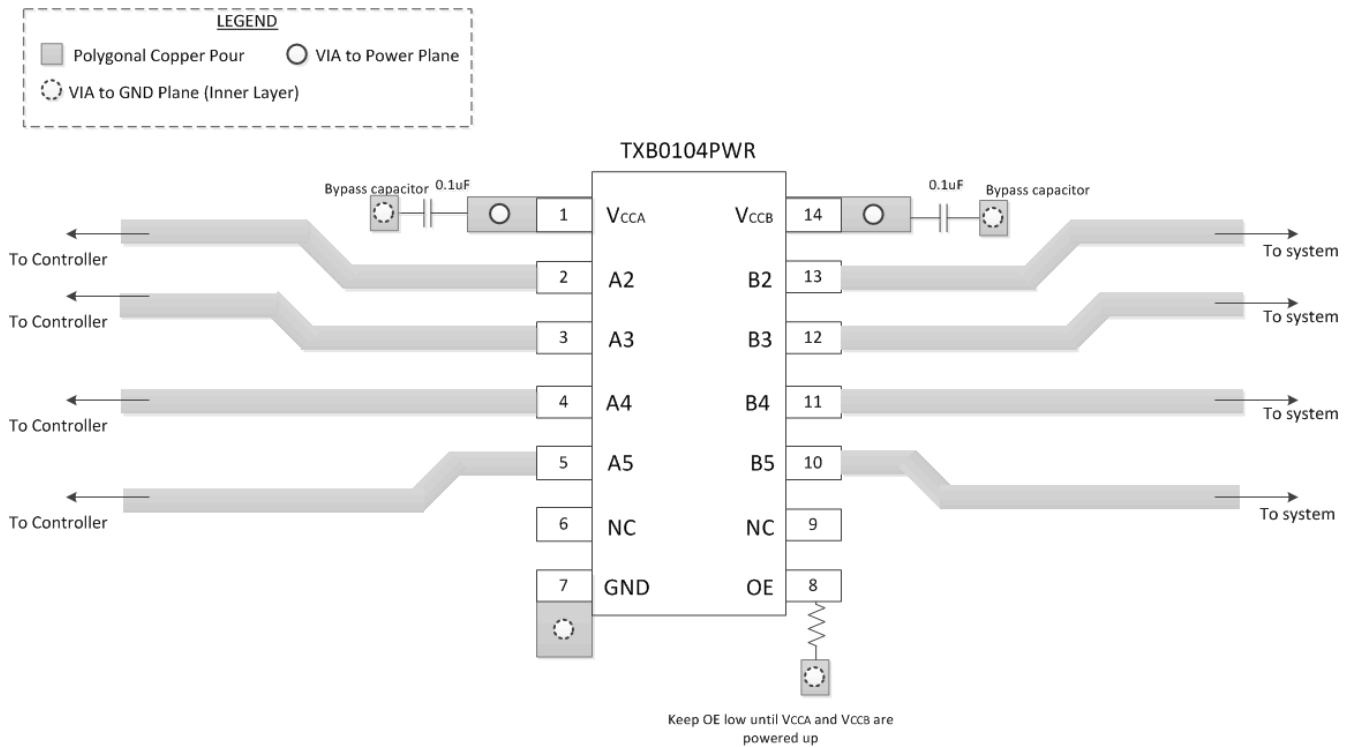


Figure 8-3. Layout Example Schematic

## 9 Device and Documentation Support

### 9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### **Changes from Revision C (November 2024) to Revision D (May 2025)** **Page**

- Updated status from Advanced Information to Production Data..... **1**
- Added thermal information for BQA package..... **6**

### **Changes from Revision B (June 2023) to Revision C (November 2024)** **Page**

- Added WQFN (14) package and body size..... **1**
- Changed all instances of 'RGY' in tables to 'RGY,BQA' throughout the document..... **1**
- Updated middle figure title to "BQA/RGY Package"..... **3**
- Added BQA column to Thermal Information table..... **6**

### **Changes from Revision A (October 2014) to Revision B (June 2023)** **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document ..... **1**

### **Changes from Revision \* (June 2008) to Revision A (October 2014)** **Page**

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes, Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ..... **1**

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">PTXB0104QWBQARQ1</a>	Active	Preproduction	WQFN (BQA)   14	3000   LARGE T&R	-	Call TI	Call TI	-40 to 125	
PTXB0104QWBQARQ1.A	Active	Preproduction	WQFN (BQA)   14	3000   LARGE T&R	-	Call TI	Call TI	-40 to 125	
<a href="#">TXB0104QPWRQ1</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YE04Q1
TXB0104QPWRQ1.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YE04Q1
TXB0104QPWRQ1.B	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YE04Q1
<a href="#">TXB0104QRGYRQ1</a>	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	YE04Q1
TXB0104QRGYRQ1.A	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	YE04Q1
TXB0104QRGYRQ1.B	Active	Production	VQFN (RGY)   14	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	YE04Q1
<a href="#">TXB0104QRUTRQ1</a>	Active	Production	UQFN (RUT)   12	3000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	SIG
TXB0104QRUTRQ1.A	Active	Production	UQFN (RUT)   12	3000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	SIG
TXB0104QRUTRQ1.B	Active	Production	UQFN (RUT)   12	3000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	SIG
<a href="#">TXB0104QWBQARQ1</a>	Active	Production	WQFN (BQA)   14	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YE04Q

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF TXB0104-Q1 :**

- Catalog : [TXB0104](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product



**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

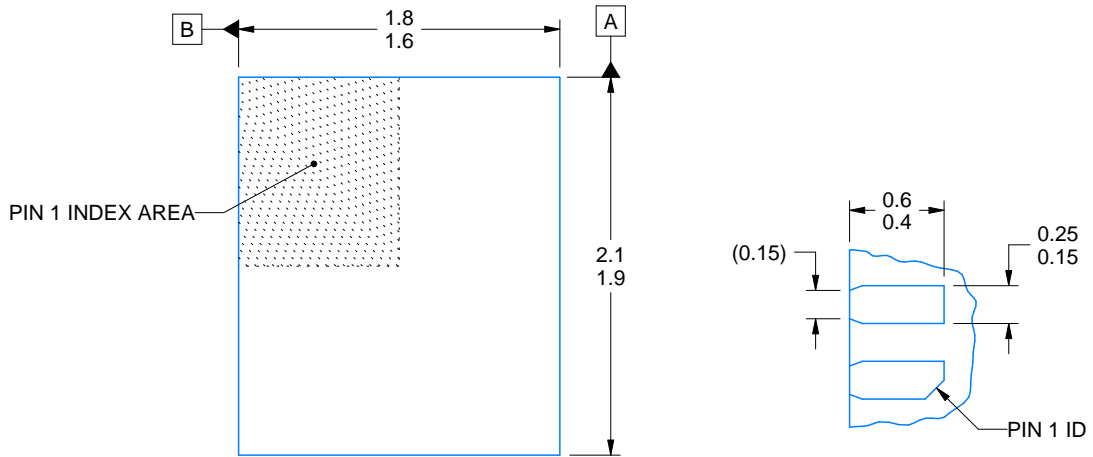
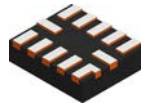
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXB0104QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TXB0104QRGYRQ1	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
TXB0104QRUTRQ1	UQFN	RUT	12	3000	180.0	8.4	1.95	2.3	0.75	4.0	8.0	Q1
TXB0104QWBQARQ1	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS

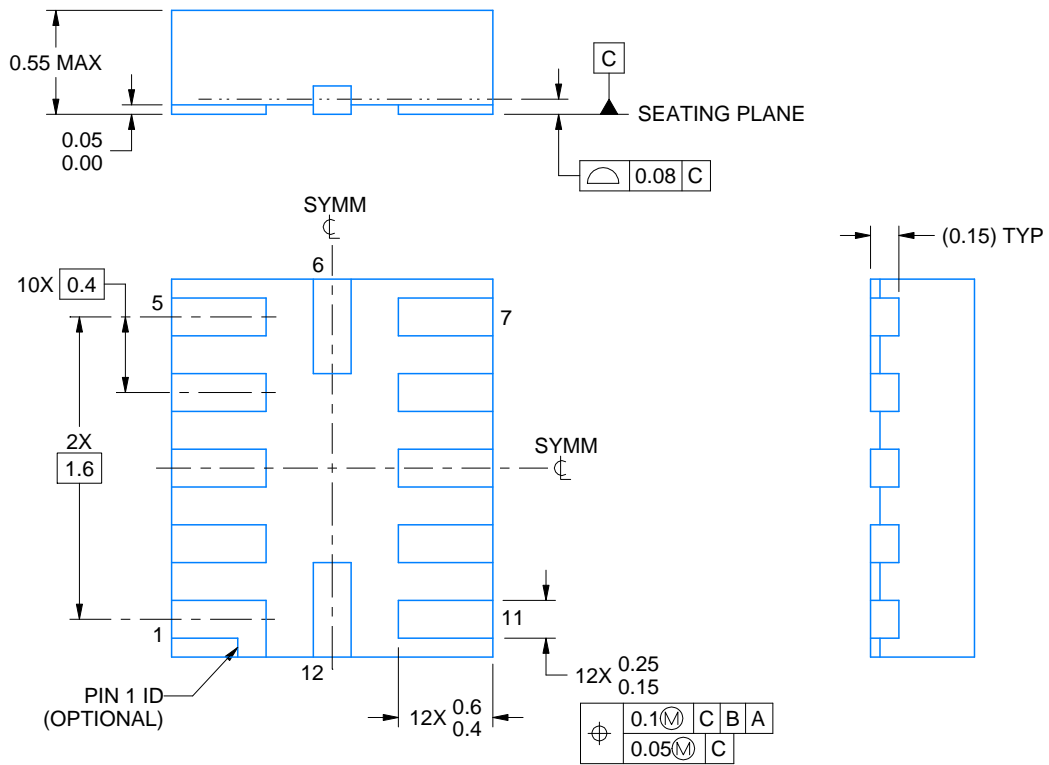


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXB0104QPWRQ1	TSSOP	PW	14	2000	353.0	353.0	32.0
TXB0104QRGYRQ1	VQFN	RGY	14	3000	353.0	353.0	32.0
TXB0104QRUTRQ1	UQFN	RUT	12	3000	202.0	201.0	28.0
TXB0104QWBQARQ1	WQFN	BQA	14	3000	210.0	185.0	35.0



OPTIONAL TERMINAL & PIN 1 ID



4220310/A 11/2016

NOTES:

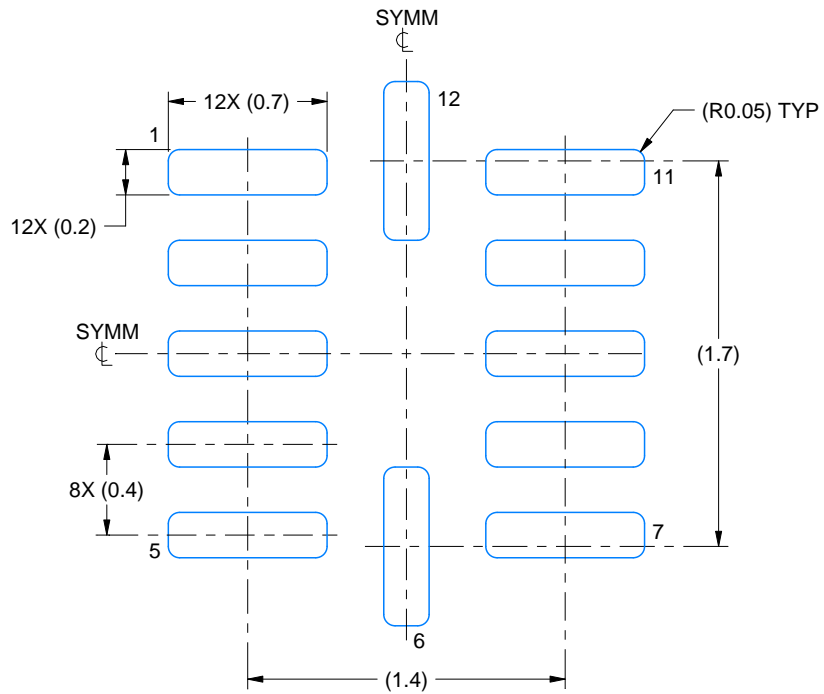
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

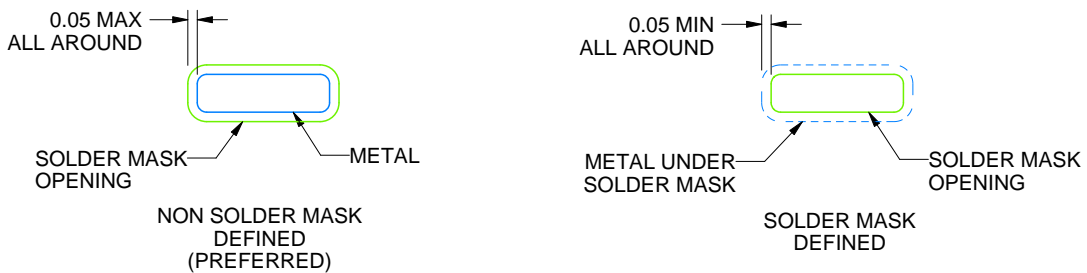
RUT0012A

UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDER MASK DETAILS

4220310/A 11/2016

NOTES: (continued)

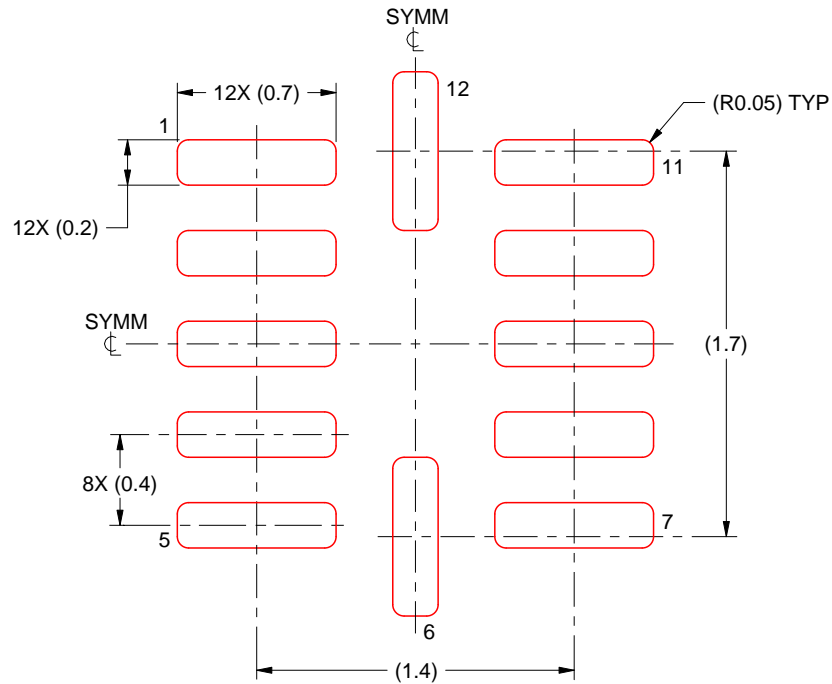
3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).

# EXAMPLE STENCIL DESIGN

RUT0012A

UQFN - 0.55 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE: 30X

4220310/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

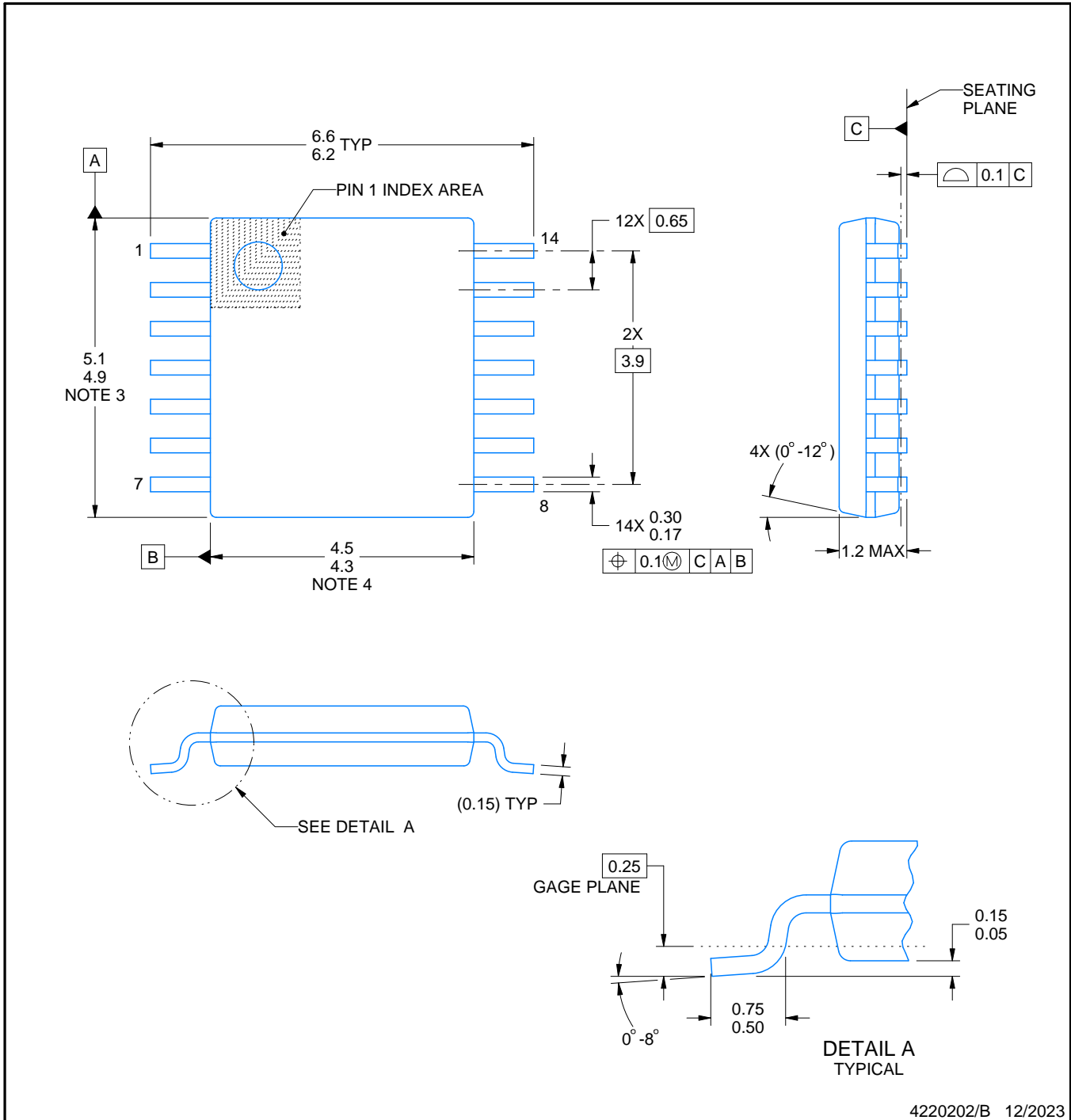
PW0014A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



## GENERIC PACKAGE VIEW

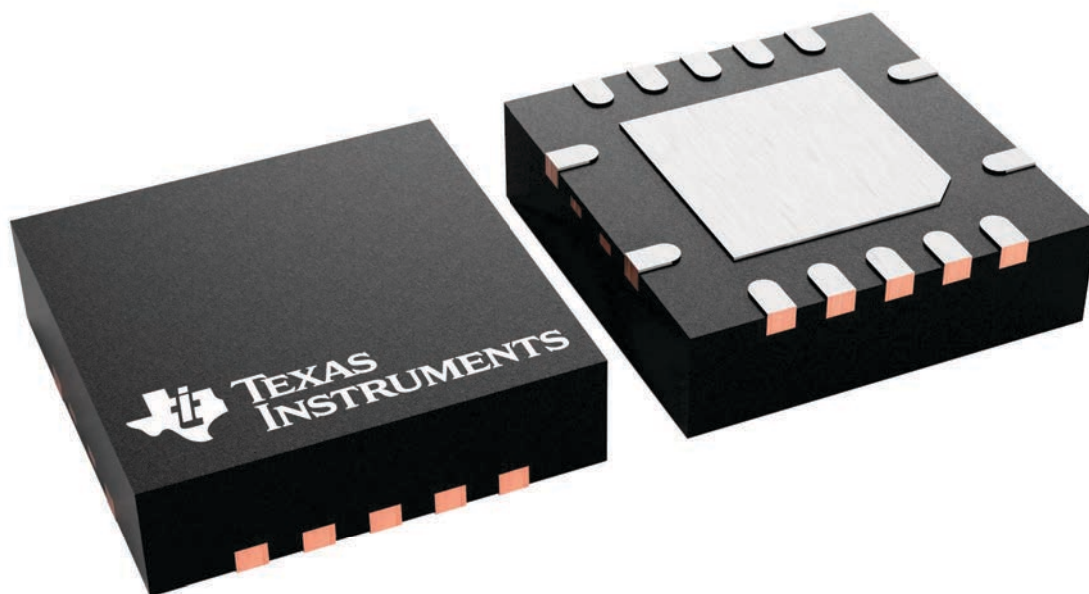
**RGY 14**

**VQFN - 1 mm max height**

3.5 x 3.5, 0.5 mm pitch

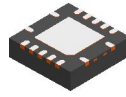
PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4231541/A

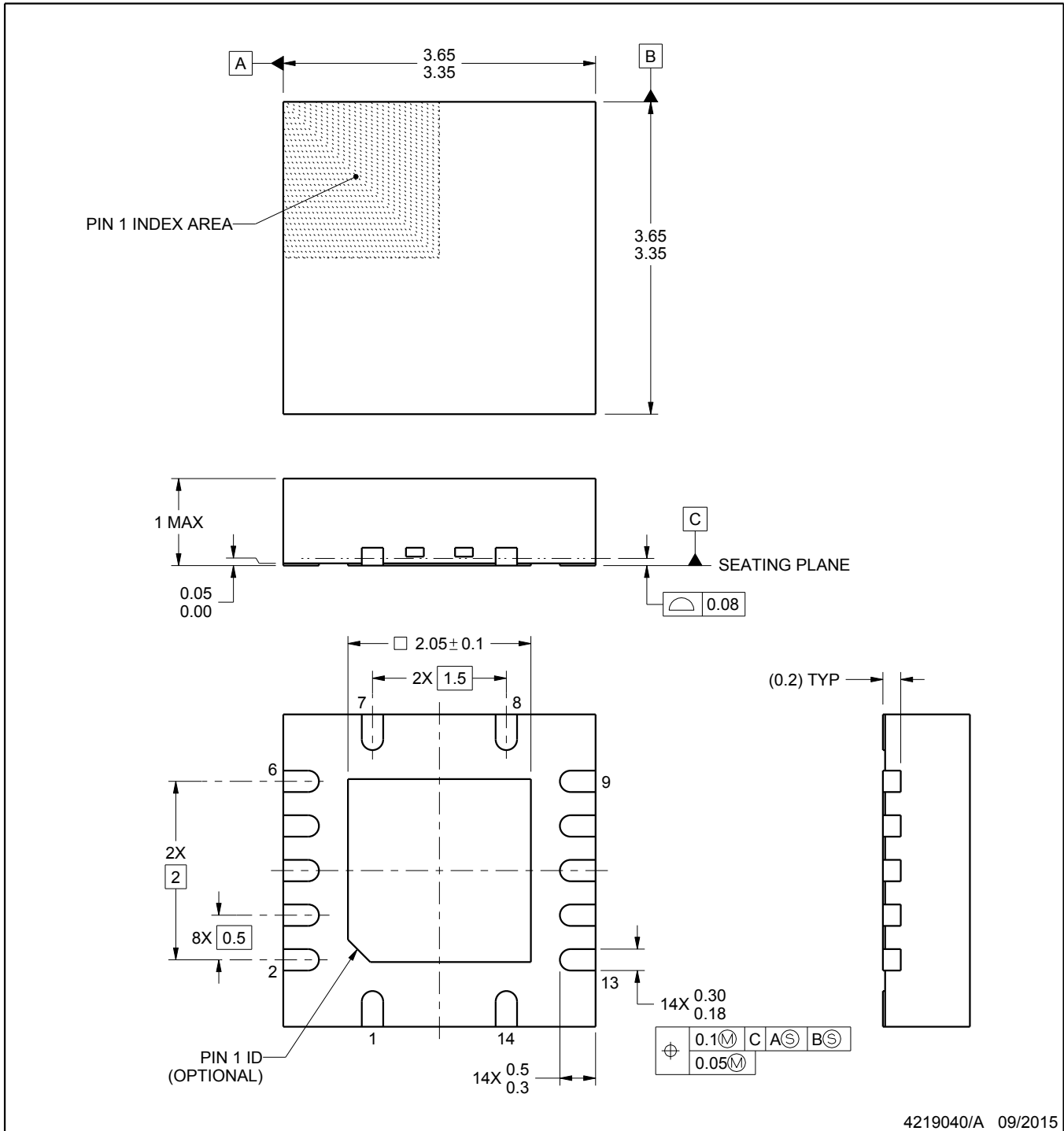
RGY0014A



PACKAGE OUTLINE

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4219040/A 09/2015

NOTES:

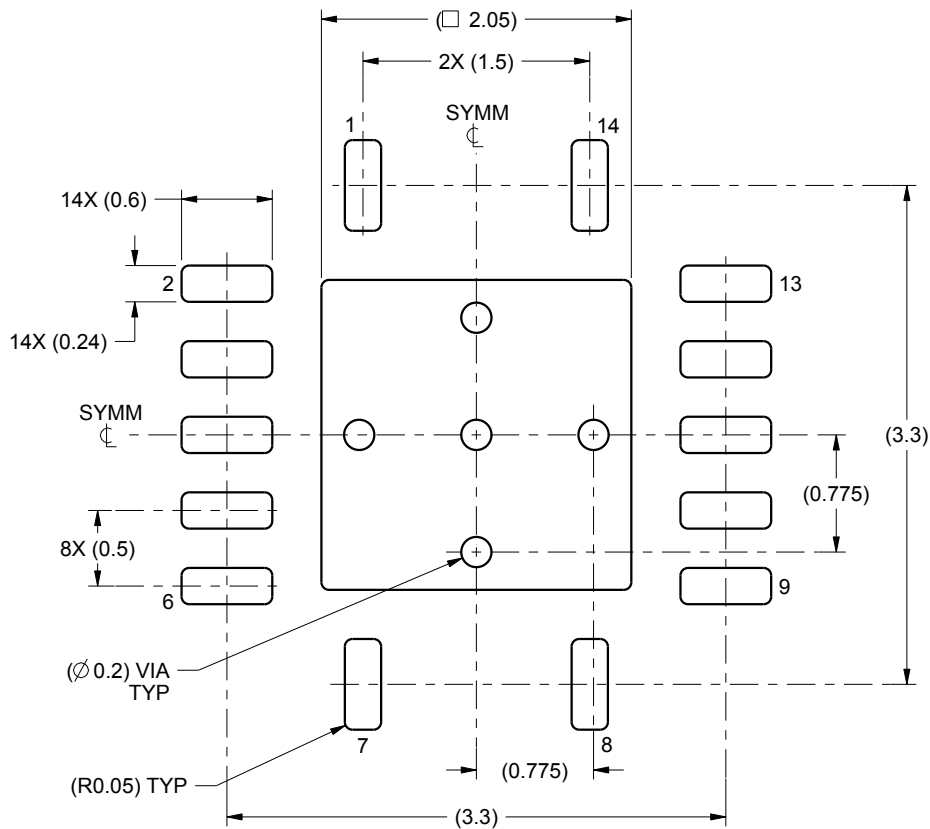
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

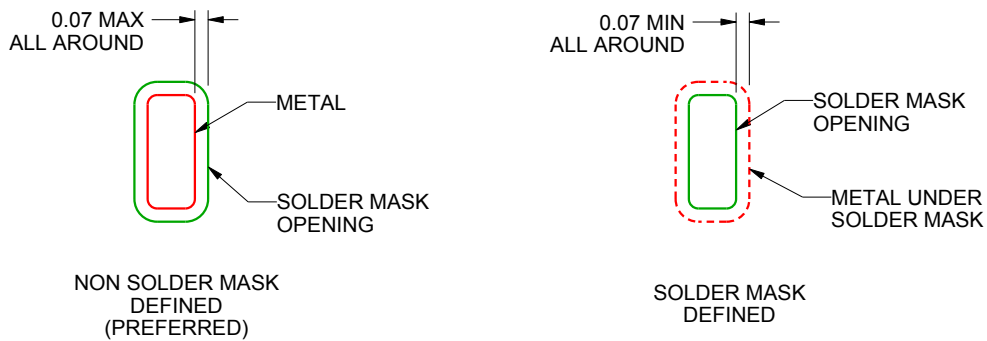
RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:20X



SOLDER MASK DETAILS

4219040/A 09/2015

NOTES: (continued)

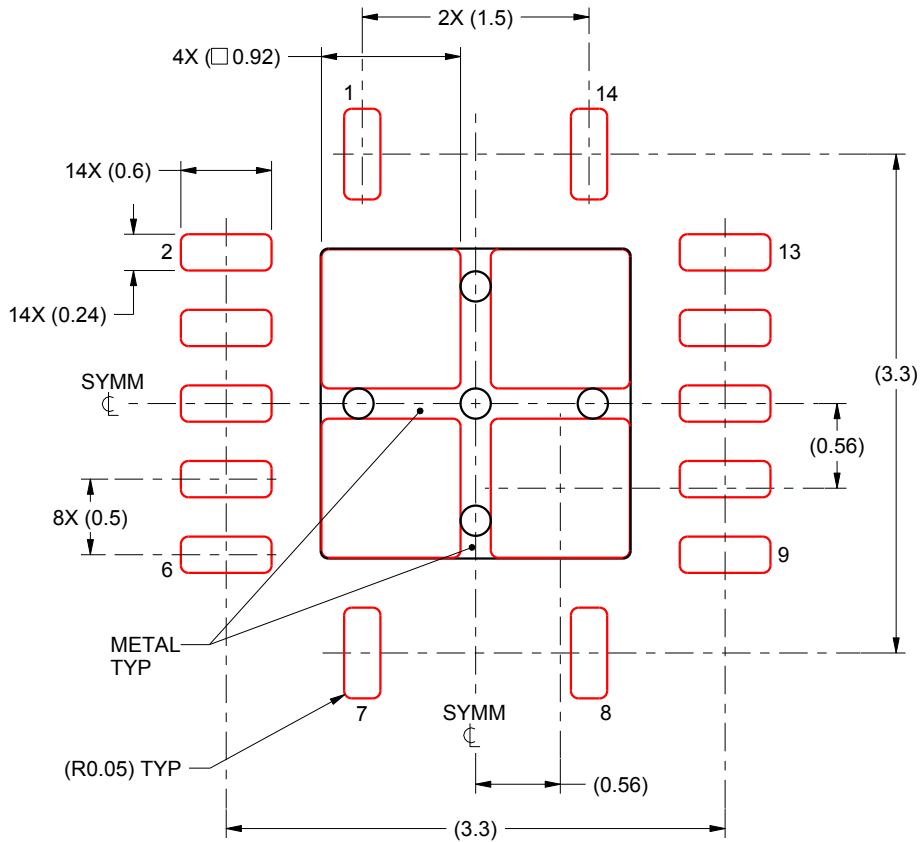
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).

# EXAMPLE STENCIL DESIGN

RGY0014A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL  
EXPOSED PAD  
80% PRINTED SOLDER COVERAGE BY AREA  
SCALE:20X

4219040/A 09/2015

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## GENERIC PACKAGE VIEW

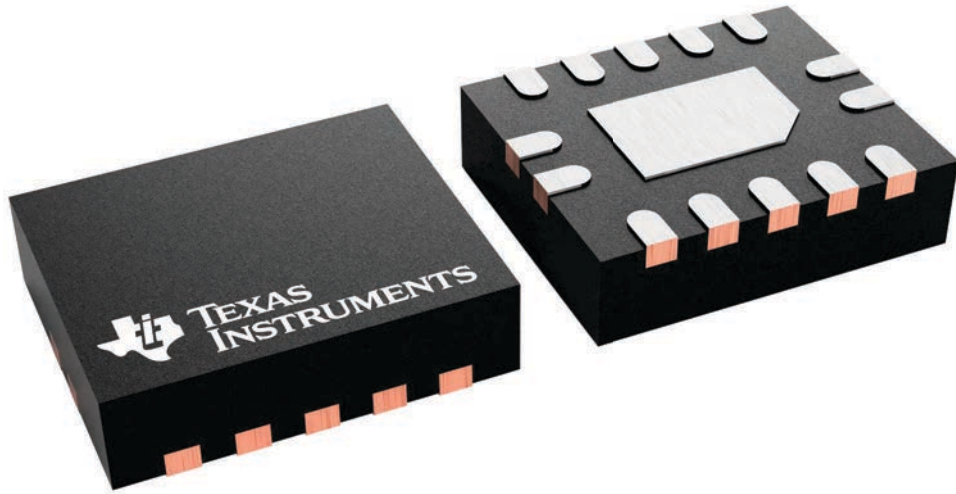
**BQA 14**

**WQFN - 0.8 mm max height**

2.5 x 3, 0.5 mm pitch

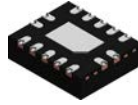
PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4227145/A

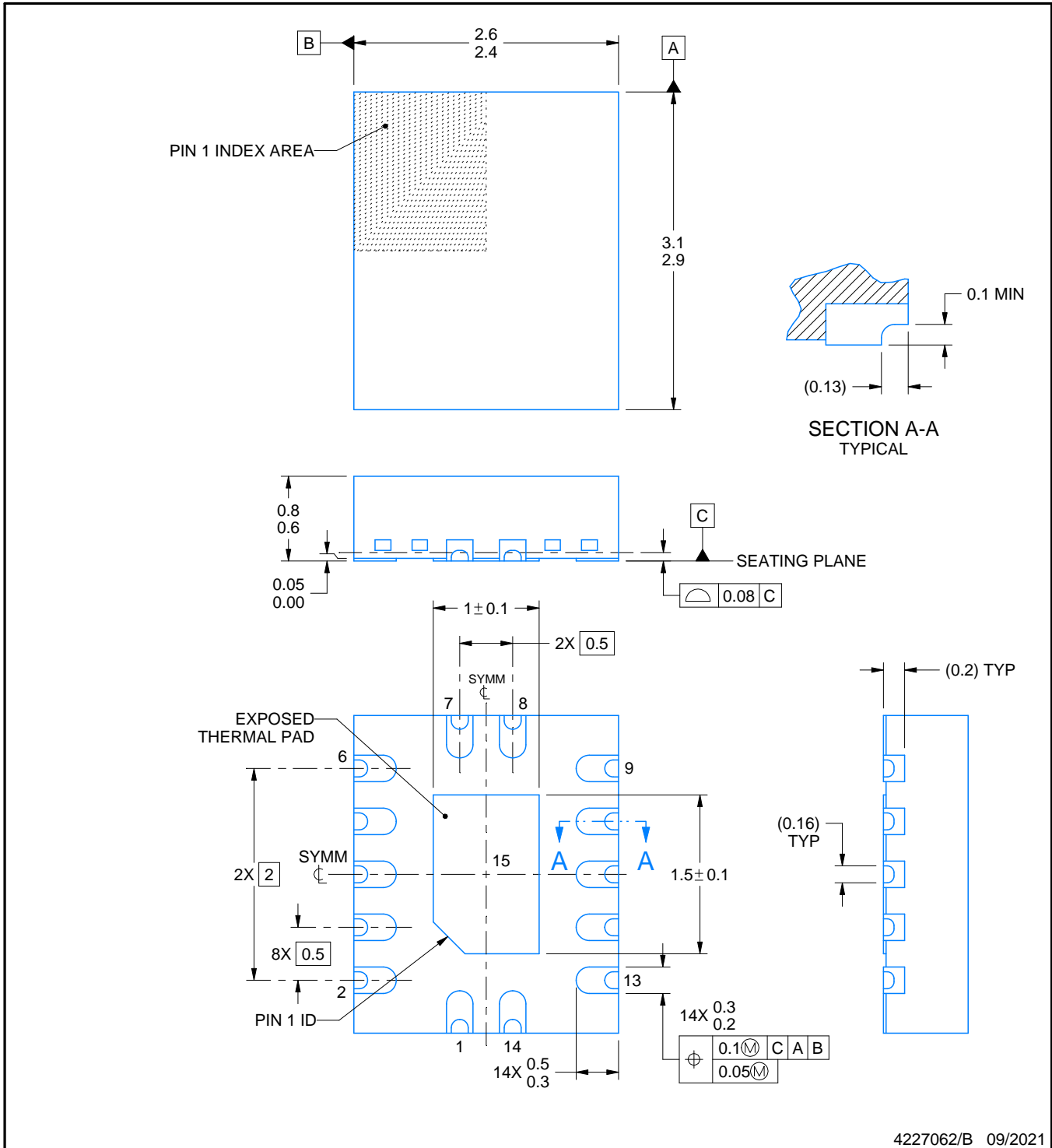
# BQA0014B



# PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4227062/B 09/2021

**NOTES:**

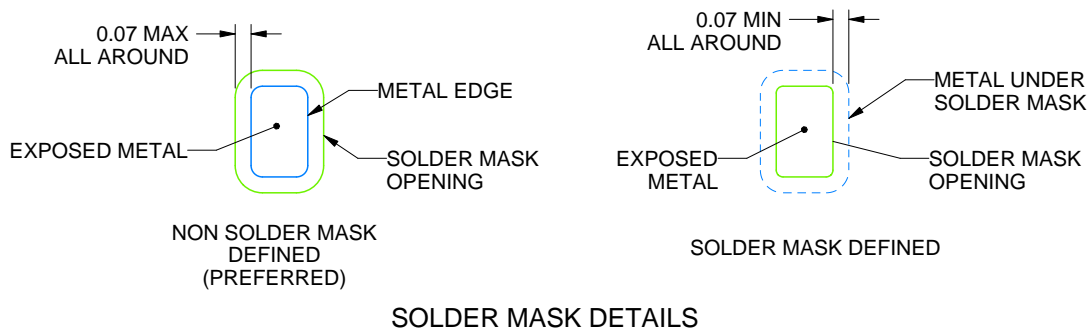
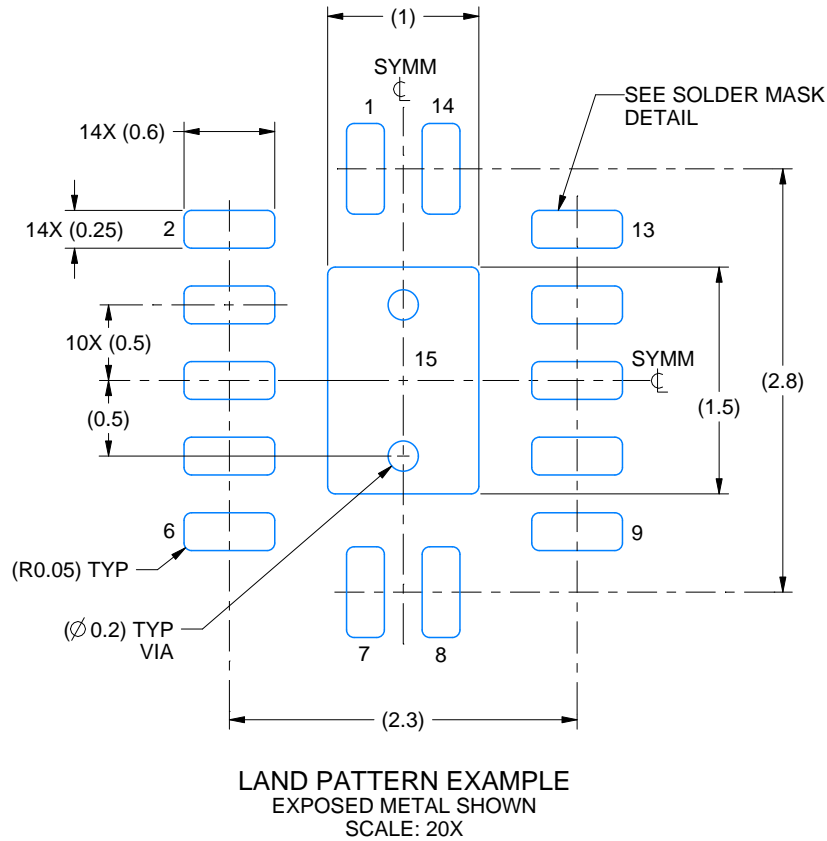
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

**BQA0014B**

**WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



4227062/B 09/2021

NOTES: (continued)

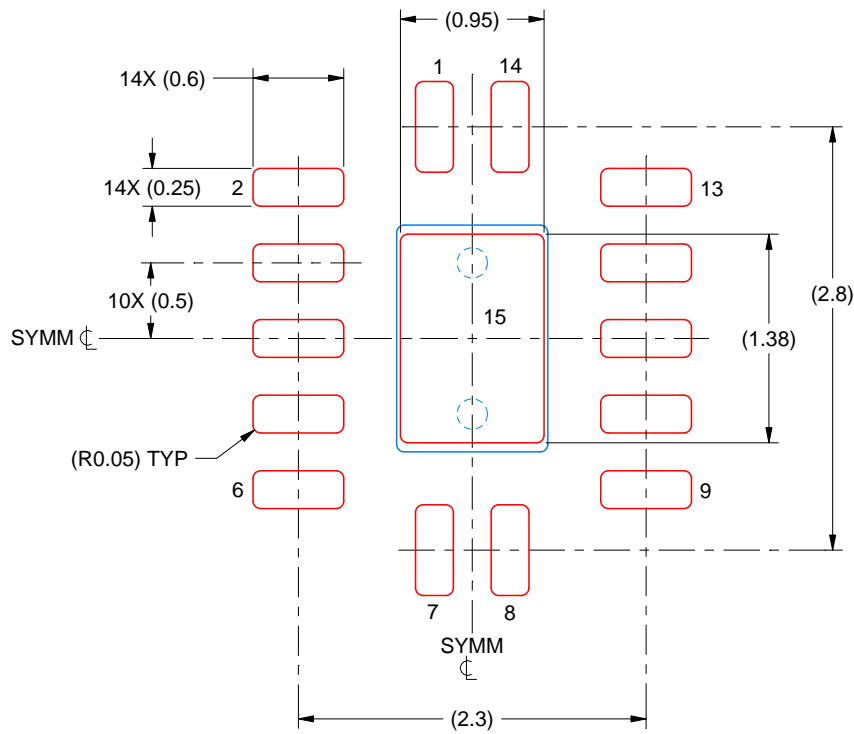
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

BQA0014B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 MM THICK STENCIL  
SCALE: 20X

EXPOSED PAD 15  
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4227062/B 09/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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Last updated 10/2025